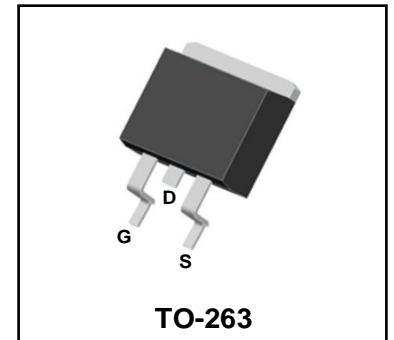


100V N-Channel Enhancement Mode Power MOSFET

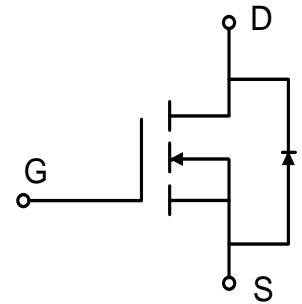
Description

WMM028N10HG2 uses Wayon's 2nd generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



Features

- $V_{DS} = 100V$, $I_D = 245A$ (Silicon Limited)
 $R_{DS(on)} < 2.8m\Omega @ V_{GS} = 10V$
- High Speed Power Switching
- Low $R_{DS(on)}$
- Low Gate Charge
- 100% EAS Guaranteed



Applications

- Hard Switching and High Speed Circuit
- DC/DC Converters
- Synchronous Rectification in SMPS

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ (Silicon Limited)	I_D	$T_C=25^\circ C$	245
		$T_C=100^\circ C$	170
Continuous Drain Current ¹ (Package Limited)		$T_C=25^\circ C$	175
Pulsed Drain Current ²	I_{DM}	780	A
Single Pulse Avalanche Energy ³	EAS	845	mJ
Avalanche Current	I_{AS}	65	A
Total Power Dissipation ⁴	P_D	$T_C=25^\circ C$	278
Operating Junction and Storage Temperature Range	$T_{J, T_{STG}}$	-55 to +150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ¹	$R_{\theta JA}$	61	$^\circ C/W$
Thermal Resistance from Junction-to-Case ¹	$R_{\theta JC}$	0.45	$^\circ C/W$

Electrical Characteristics $T_c = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100	-	-	V
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	± 100	nA
Zero Gate Voltage Drain Current	$T_J=25^\circ\text{C}$	$V_{DS} = 100V, V_{GS} = 0V$	-	-	10	μA
	$T_J=100^\circ\text{C}$		-	-	100	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-Source on-Resistance ²	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	2.3	2.8	m Ω
Forward Transconductance ²	g_{fs}	$V_{DS} = 5V, I_D = 20A$	-	70	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 50V, V_{GS} = 0V, f = 1\text{MHz}$	-	7735	-	μF
Output Capacitance	C_{oss}		-	1190	-	
Reverse Transfer Capacitance	C_{rss}		-	25	-	
Switching Characteristics						
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1\text{MHz}$	-	1.4	-	Ω
Total Gate Charge	Q_g	$V_{GS} = 10V, V_{DS} = 50V, I_D = 20A$	-	98	-	nC
Gate-Source Charge	Q_{gs}		-	20	-	
Gate-Drain Charge	Q_{gd}		-	18	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 50V, R_G = 10\Omega, I_D = 20A$	-	25	-	nS
Rise Time	t_r		-	20	-	
Turn-off Delay Time	$t_{d(off)}$		-	50	-	
Fall Time	t_f		-	11	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$I_S = 20A, V_{GS} = 0V$	-	-	1.2	V
Continuous Source Current ^{1,5}	I_S	$V_G = V_D = 0V, \text{Force Current}$	-	-	245	A
Reverse Recovery Time	t_{rr}	$V_R = 50V, I_F = 20A, di/dt = 500A/\mu s$	-	60	-	nS
Reverse Recovery Charge	Q_{rr}		-	438	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is $V_{DD} = 25V, V_{GS} = 10V, L = 0.4\text{mH}, I_{AS} = 65A$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

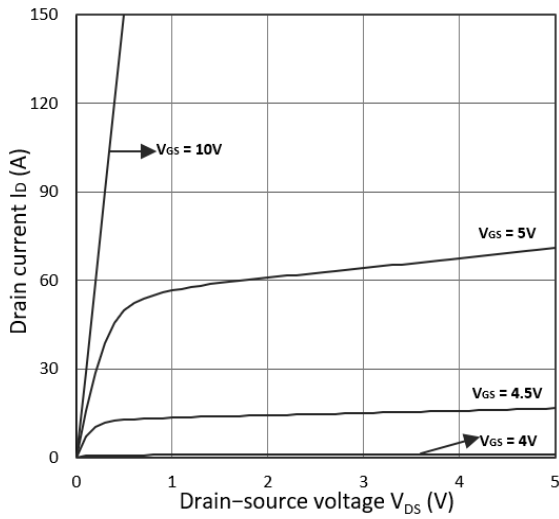


Figure 1. Output Characteristics

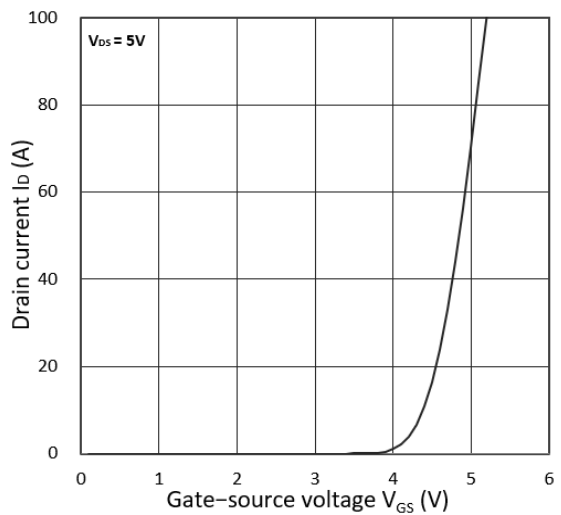


Figure 2. Transfer Characteristics

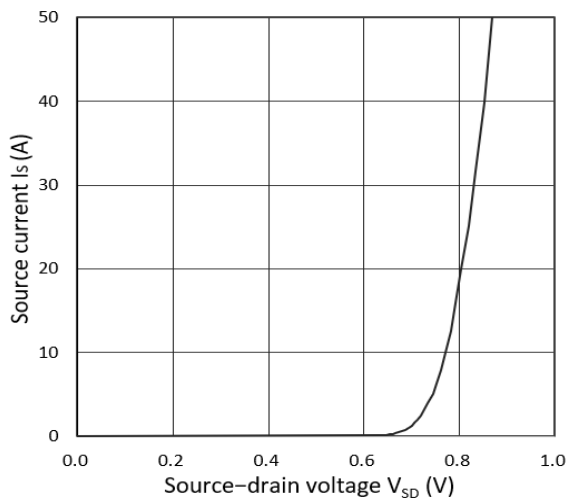


Figure 3. Forward Characteristics of Reverse

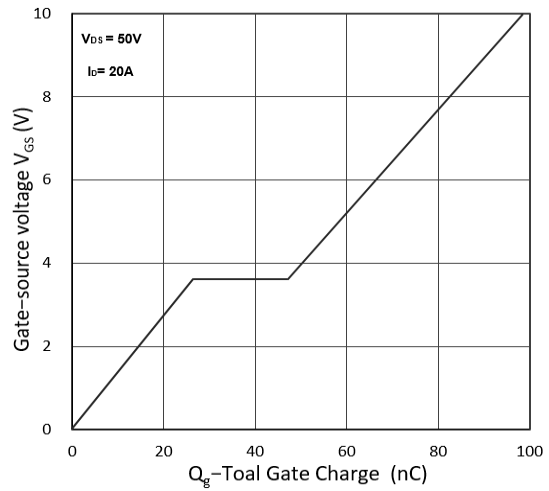


Figure 4. Gate Charge Characteristics

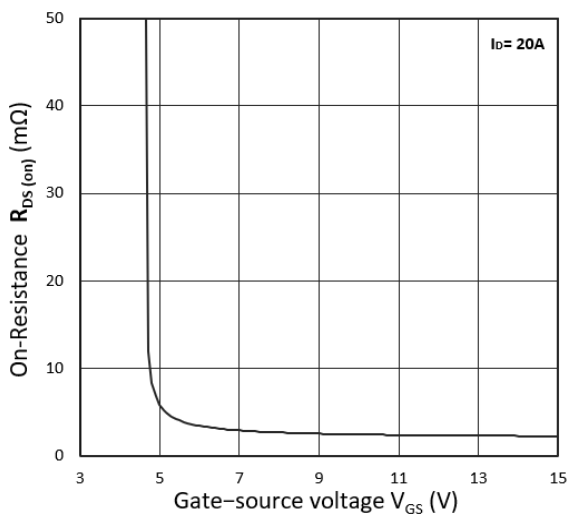


Figure 5. $R_{DS(on)}$ vs. V_{GS}

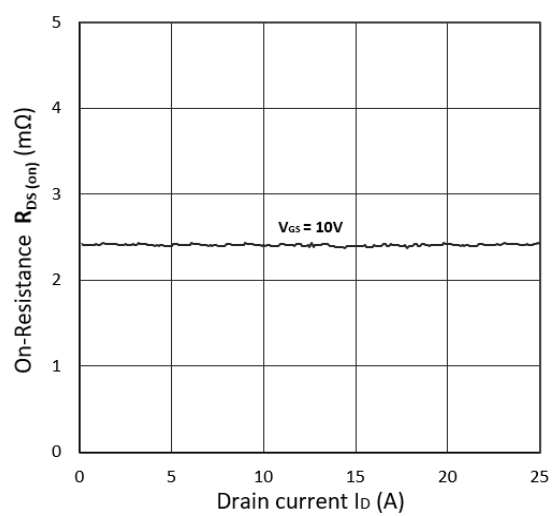


Figure 6. $R_{DS(on)}$ vs. I_D

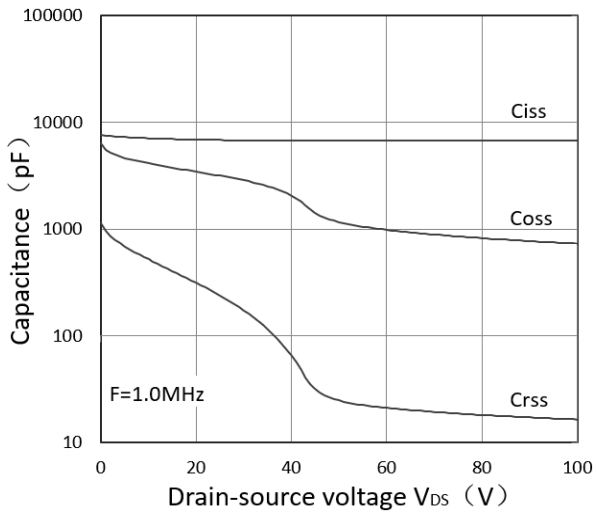


Figure 7. Capacitance Characteristics

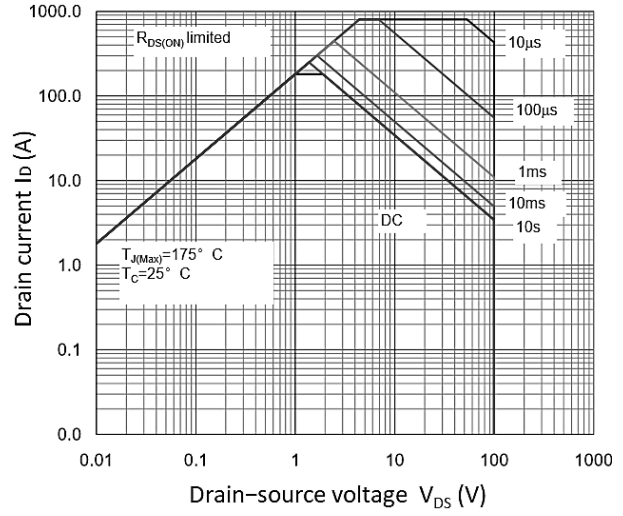


Figure 8. Safe Operating Area

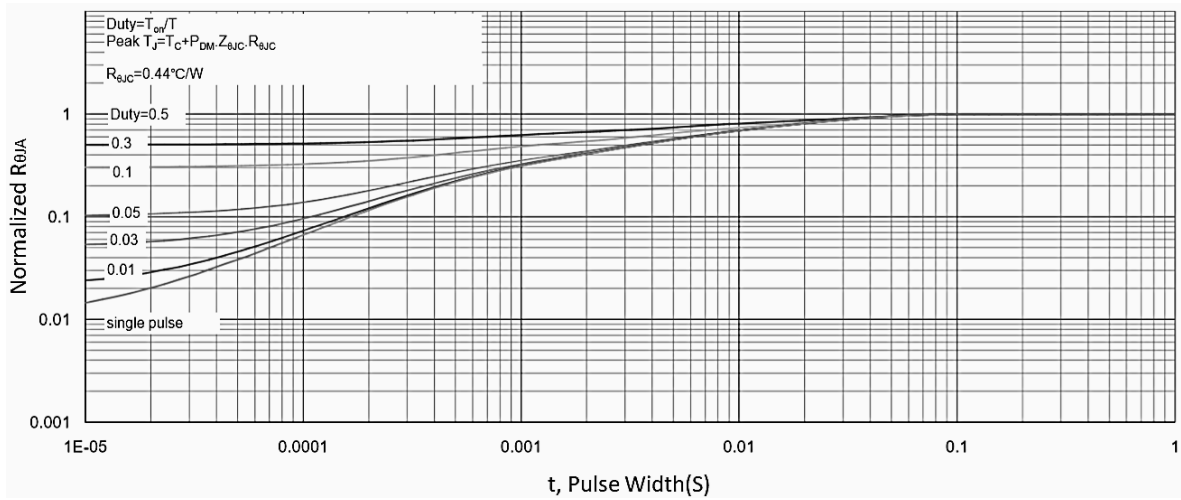


Figure 9. Normalized Maximum Transient Thermal Impedance

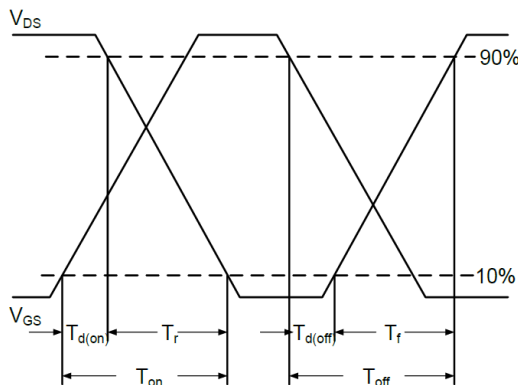


Figure 10. Switching Time Waveform

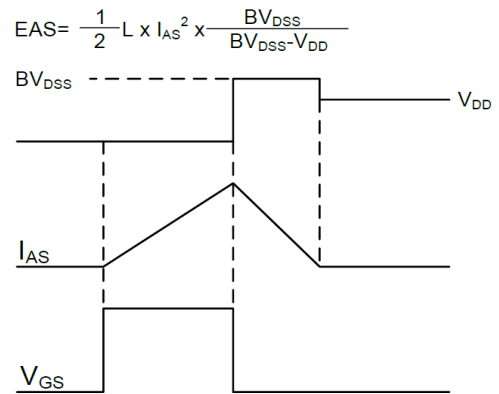
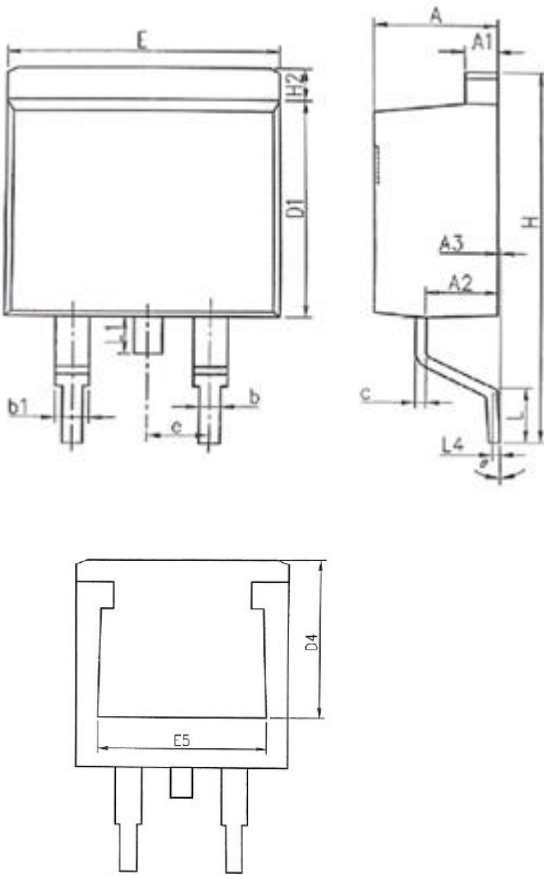


Figure 11. Unclamped Inductive Switching Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Mechanical Dimensions for TO-263

COMMON DIMENSIONS

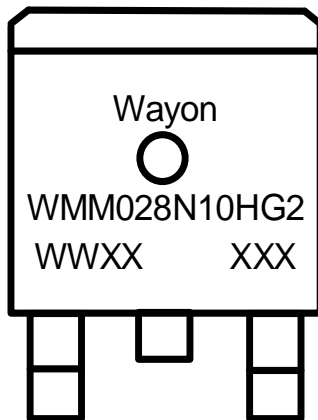


SYMBOL	MM	
	MIN	MAX
A	4.37	4.77
A1	1.22	1.42
A2	2.20	2.90
A3	0.00	0.25
b	0.70	0.96
b1	1.17	1.47
c	0.30	0.60
D1	8.50	9.30
D4	6.60	-
E	9.80	10.36
E5	7.06	-
e	2.54BSC	
H	14.70	15.70
H2	1.07	1.47
L	2.00	2.60
L1	-	1.75
L4	0.254BSC	
θ	0°	9°

Ordering Information

Part	Package	Marking	Packing method
WMM028N10HG2	TO-263	WMM028N10HG2	Tape and Reel

Marking Information



WMM028N10HG2 = Device code

WWXX XXX = Date code


Contact Information

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WAYON website: <http://www.way-on.com>

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